

RESIN COMPOSITION AND
HYBRID INTEGRATED CIRCUIT BOARD MAKING USE OF THE SAME

ABSTRACT

A substrate, a circuit board and a multilayer circuit board are provided which, although being made of an inorganic filler as a crushed product, are capable of providing a highly reliable hybrid integrated circuit because of having excellent adhesion to a metal plate or metal foil and exhibiting a high thermal conductivity.

A resin composition comprising a curable resin comprising an epoxy resin and a curing agent for the epoxy resin; and an inorganic filler filled in the curable agent; wherein the curing agent comprises a phenol novolak resin, and wherein the inorganic filler comprises a coarse powder containing particles having an average particle size of 5 to 20 μm , preferably particles having a maximum particle size of 100 μm or below and a particle size of 5 to 50 μm in an amount of 50 vol% or above; and a fine powder containing particles having an average particle size of 0.2 to 1.5 μm , preferably particles having a particle size of 2.0 μm or below in an amount of 70 vol% or above. A substrate for a hybrid integrated circuit, a circuit board and a multilayer circuit board, which use the resin composition.

NO FIGURE